



FINAL PRODUCT/PROCESS CHANGE NOTIFICATIONGeneric Copy

07 Jan 2010**SUBJECT:** ON Semiconductor Final Product/Process Change Notification #16384**TITLE:** Qualification of NCP347, NCP348, NCP349 for Fabrication at ON Semiconductor Gresham Wafer Fab**PROPOSED FIRST SHIP DATE:** 07 Apr 2010 or earlier with customer approval**AFFECTED CHANGE CATEGORY(S):** ON Semi Fab Site**AFFECTED PRODUCT DIVISION(S):** Computing and Consumer Products Group**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Todd Manes<todd.manes@onsemi.com>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Todd Manes<todd.manes@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce that the NCP347, NCP348, and NCP349 product families are now qualified for production at ON Semiconductor's Gresham wafer fab (located in Gresham, Oregon).

Upon expiration or approval of the Final PCN, devices may be supplied from the Gresham wafer fab.

The Gresham wafer fab is compliant to ISO9001:2000, ISO/TS16949:2002, and ISO14001:2004. The devices have previously been manufactured at ON Semiconductor's Piastany, Slovakia wafer fab on the 0.8um PS5LV process. Devices are now qualified to run at Gresham on the 0.25um BCD process. Device performance is the same for the Gresham-sourced material as for the Piastany-sourced material. All devices continue to be assembled and tested in existing, qualified locations. No changes to packaging occur as a result of this wafer fab qualification.

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Products sourced from the Gresham wafer fab continue to meet ON Semiconductor's standards and requirements. Reliability test results for Gresham qualification material are summarized below.

Reliability Test Results:

Test	Conditions	Results
HTOL	NCP347MTAHTBG, Tj=+150C, 336 hours	Pass
ESD:	NCP347MTAITBG, 2000V HBM	Pass
	NCP347MTAITBG, 200V MM	Pass
LU:	NCP347MTAITBG, Class II +85C (100mA)	Pass

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no significant difference in electrical parametric performance for the Gresham-sourced material. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

Products listed in this PCN with Finished Good date codes representing WW 14, 2010 or later will be assembled with die sourced from the Gresham wafer fab, unless earlier customer approval is obtained. If early customer approval is obtained, devices with date codes of WW 03, 2010 or later will be assembled with die from the Gresham wafer fab.



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AFFECTED DEVICE LIST

NCP347MTAETBG
NCP347MTAITBG
NCP347MTAFTBG
NCP347MTAHTBG
NCP348AEMTTBG
NCP348AEMUTBG
NCP348MTTBG
NCP349MNAETBG
NCP349MNBGTBG
NCP349MNBKTBG
NCP349MNTBG